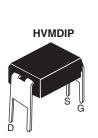
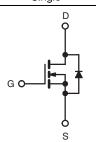


Power MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	10	100				
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V	0.27				
Q _g (Max.) (nC)	16	16				
Q _{gs} (nC)	4.4	4.4				
Q _{gd} (nC)	7.7	7.7				
Configuration	Sino	Single				





N-Channel MOSFET

FEATURES

- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- For Automatic Insertion
- End Stackable
- 175 °C Operating Temperature
- Fast Switching
- Ease of Paralleling
- Compliant to RoHS Directive 2002/95/EC

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The 4 pin DIP package is a low cost machine-insertable case style which can be stacked in multiple combinations on standard 0.1" pin centers. The dual drain serves as a thermal link to the mounting surface for power dissipation levels up to 1 W.

ORDERING INFORMATION			
Package	HVMDIP		
Lead (Pb)-free	IRFD120PbF		
Lead (FD)-life	SiHFD120-E3		
SnPb	IRFD120		
JIII D	SiHFD120		

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	100		
Gate-Source Voltage			V_{GS}	± 20	- V	
Continuous Drain Current	\/ at 10.\/	T _A = 25 °C T _A = 100 °C	I _D	1.3	А	
Continuous Drain Current	V _{GS} at 10 V	T _A = 100 °C		0.94		
Pulsed Drain Current ^a			I _{DM}	10	1	
Linear Derating Factor				0.0083	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	100	mJ	
Repetitive Avalanche Current ^a			I _{AR}	1.3	А	
Repetitive Avalanche Energy ^a			E _{AR}	0.13	mJ	
Maximum Power Dissipation	T _A = 25 °C		P_{D}	1.3	W	
Peak Diode Recovery dV/dt ^c			dV/dt	5.5	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 175		
Soldering Recommendations (Peak Temperature)	for	10 s	-	300 ^d	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. V_{DD} = 25 V, starting T_J = 25 °C, L = 22 mH, R_g = 25 Ω , I_{AS} = 2.6 A (see fig. 12).
- c. $I_{SD} \le 9.2$ A, $dI/dt \le 110$ A/µs, $V_{DD} \le V_{DS}$, $T_J \le 175$ °C.
- d. 1.6 mm from case.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply

IRFD120, SiHFD120

Vishay Siliconix



THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum Junction-to-Ambient	R_{thJA}	-	120	°C/W		

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA		100	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	ce to 25 °C, I _D = 1 mA	-	0.13	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} :	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 20 V	-	-	± 100	nA
Zon Cala Vallana Buria Comal	I _{DSS}	V _{DS} :	V _{DS} = 100 V, V _{GS} = 0 V		-	25	
Zero Gate Voltage Drain Current		V _{DS} = 80 V	', V _{GS} = 0 V, T _J = 150 °C	-	-	250	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	$I_D = 0.78 A^b$	-	-	0.27	Ω
Forward Transconductance	9 _{fs}	V _{DS} =	50 V, I _D = 0.78 A ^b	0.80	-	-	S
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0 V		-	360	-	
Output Capacitance	C _{oss}]	$V_{DS} = 25 \text{ V}$	-	150	-	pF
Reverse Transfer Capacitance	C _{rss}	f = 1.0 MHz, see fig. 5		-	34	-	1
Total Gate Charge	Qg		I _D = 9.2 A, V _{DS} = 80 V see fig. 6 and 13 ^b	-	-	16	nC
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V		-	-	4.4	
Gate-Drain Charge	Q _{gd}			-	-	7.7	
Turn-On Delay Time	t _{d(on)}	V_{DD} = 50 V, I_{D} = 9.2 A R_{g} = 18 Ω , R_{D} = 5.2 Ω , see fig. 10 ^b		-	6.8	-	- ns
Rise Time	t _r			-	27	-	
Turn-Off Delay Time	t _{d(off)}			-	18	-	
Fall Time	t _f			-	17	-	
Internal Drain Inductance	L_D	6 mm (0.25") f	Between lead, 6 mm (0.25") from		4.0	-	nH
Internal Source Inductance	L _S	package and center of die contact		-	6.0	-	
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	1.3	A
Pulsed Diode Forward Current ^a	I _{SM}			-	-	10	_ ^
Body Diode Voltage	V_{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 1.3 \text{A}, V_{GS} = 0 \text{V}^{\text{b}}$		-	-	2.5	V
Body Diode Reverse Recovery Time	t _{rr}	T 05 00 1	0.0 A 41/4+ 400 A / b	-	130	260	ns
Body Diode Reverse Recovery Charge	Q _{rr}	$T_{\rm J} = 25~{\rm ^{\circ}C}, I_{\rm F} = 9.2~{\rm A}, dI/dt = 100~{\rm A/\mu s^{b}}$		-	0.65	1.3	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)				L _D)	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b. Pulse width \leq 300 µs; duty cycle \leq 2 %.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

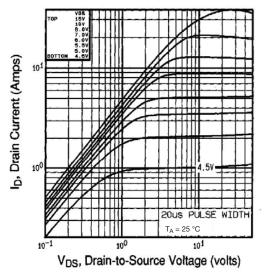


Fig. 1 - Typical Output Characteristics, $T_A = 25$ °C

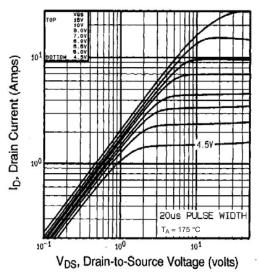


Fig. 2 - Typical Output Characteristics, T_A = 175 °C

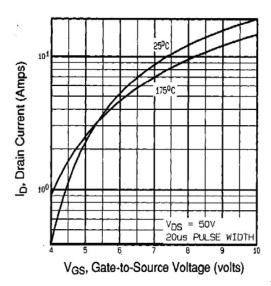


Fig. 3 - Typical Transfer Characteristics

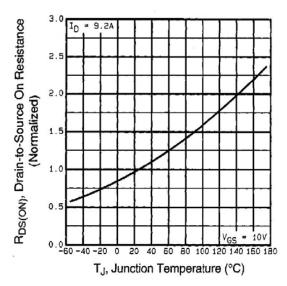


Fig. 4 - Normalized On-Resistance vs. Temperature



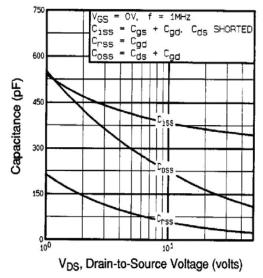


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

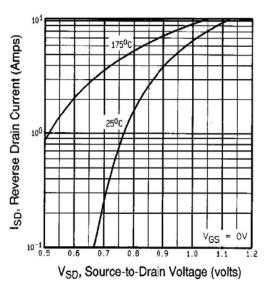


Fig. 7 - Typical Source-Drain Diode Forward Voltage

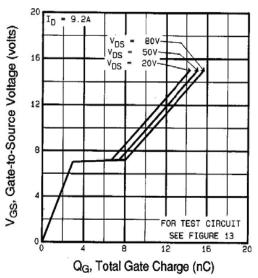


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

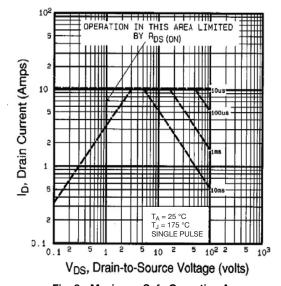


Fig. 8 - Maximum Safe Operating Area





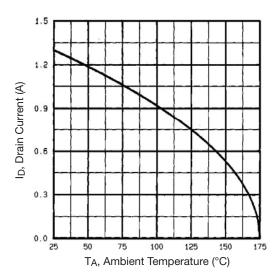


Fig. 9 - Maximum Drain Current vs. Ambient Temperature

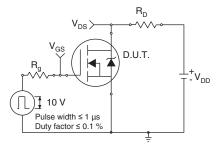


Fig. 10a - Switching Time Test Circuit

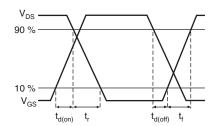


Fig. 10b - Switching Time Waveforms

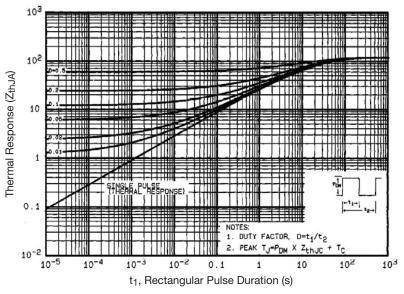


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



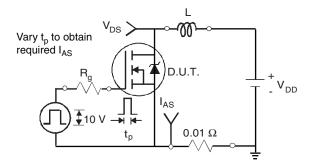


Fig. 12a - Unclamped Inductive Test Circuit

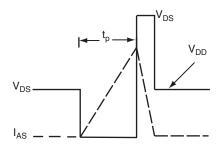


Fig. 12b - Unclamped Inductive Waveforms

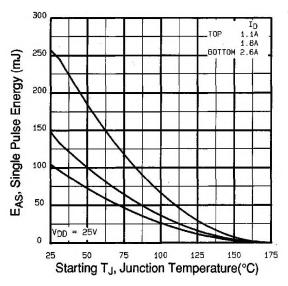


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

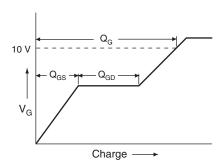


Fig. 13a - Basic Gate Charge Waveform

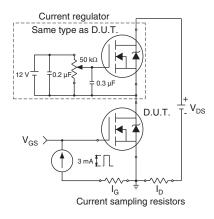
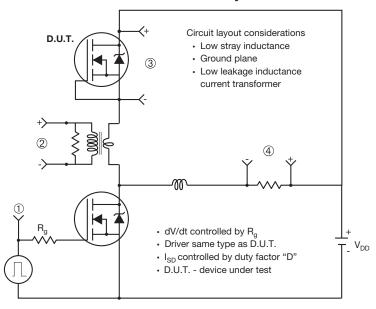


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



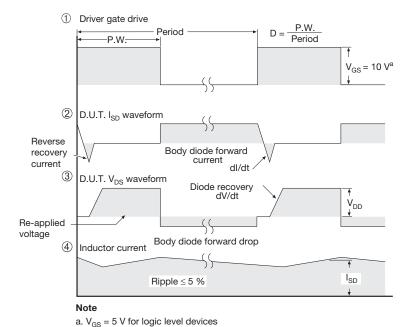
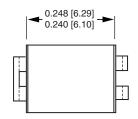
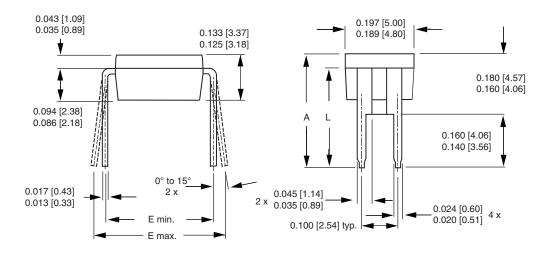


Fig. 14 - For N-Channel

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HVM DIP (High voltage)





	INCHES		MILLIMETERS		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	0.310	0.330	7.87	8.38	
E	0.300	0.425	7.62	10.79	
L	0.270	0.290	6.86	7.36	

ECN: X10-0386-Rev. B, 06-Sep-10

DWG: 5974

1. Package length does not include mold flash, protrusions or gate burrs. Package width does not include interlead flash or protrusions.

Document Number: 91361 Revision: 06-Sep-10



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Revision: 02-Oct-12 Document Number: 91000

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